(Rev. 6-93) KEC OMB No. 0651-0011 (exp. 4/94)	ORDATION PATE		U.S. DEPARTMENT OF COMN Patent and Trademark
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To the Honorable Commissioner of		100796792	Jocuments or copy thereof.
1. Name of conveying party(ies):	MAD	2. Name and address of receiv	ing party(ies)
Yutaka Nakagawa	8-13-98	Name: SONY CORPORATION	
Katsuhiki Ueno		Internal Address: a Japane	•
		internal Address: a sapari	ese Corporation
Additional name(s) of conveying party(ies) atta	ached? 🗌 Yes 🛛 No		
3. Nature of conveyance:		Street Address: 7-35 Kitashinagawa, 6-Chome	
Assignment] Merger		
Security Agreement Change of Name		City: Shinagawa-Ku State: Tokyo	
Other		Country: Japan	
Execution Date: July 31, 1998 and August 3, 1998		Additional name(s) & address(es) attashed? 🗌 Yes 🛛 No	
4. Application number(s) or patent number			
If this document is being filed together	with a new application, t		on is:
A. Patent Application No.(s)		B. Patent No.(s)	
09/090,288			
	Additional numbers a	t attached? 🗌 Yes 🛛 No	
 Name and address of party to whom correspondence concerning document should be mailed: 		6 Total Number of applications and patents involved: 1	
Internal Address: LERNER, DAVID, LITTENBERG,		Enclosed	
KRUMHOLZ & MENTLIK, LLP		Authorized to be charged to deposit account	
Street Address: 600 South Avenue West		8. Deposit account number:	
City: Westfield State: NJ ZIP: 07090		12-1095	
City, Wobillora Build, 19		(Attach duplicate copy of this pag	e if paying by deposit account)
	DO NOT US	E THIS SPACE	
9. Statement and signature. To the best of my knowledge and beliej original document.	f, the foregoing informati	on is true and correct and any att	tached copy is a true copy of the
MARCUS J. MILLET	the second secon	1_	August 11, 1998
Name of Person Signing	Signati	ure	Date
19/1998 TTON11 00000043 121095 090908	hundber of pages including cove	er sheet, attachments, and document: 3	
FC:581 40.00 CH			

U.S. Patent and Trademark Office, Office of Public Records, Crystal Gateway 4, Room 335, Washington PC 20231 Attention: Assignments REEL: 9382 FRAME: 0417

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in: CAMERA APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$ 1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property. Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention. applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 09/090.288 , Filing Date: June 4, 1998

This assignment executed on the dates indicated below.

Yutaka Nakagawa Name of First or Sole Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan Residence of First or Søle Inventor

Signature of First or Sole Inventor Date of this Assignment

Kataukika Haur	3. Aug. 12	
Katsuhiko Ueno Name of Second Joint Inventor	Execution Date of U.S. Patent Application	
Kanagawa, Japan Residence of Second Joint Inventor		
Cathites Liens	3. Aug 13	
Signature of Second Joint Inventor	Date of this Assignment	
Name of Third Joint Inventor	Execution Date of U.S. Patent Application	
Residence of Third Joint Inventor		
Signature of Third Joint Inventor	Date of this Assignment	

Signature of Third Joint Inventor

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